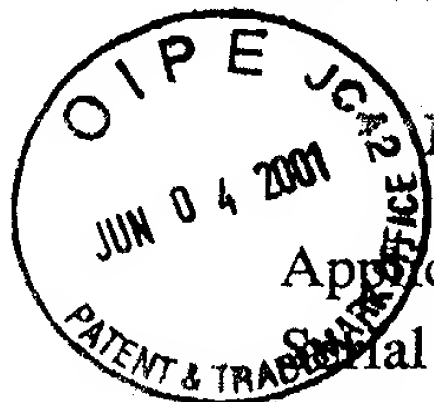


EN995141V

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Bernd K. Appelt et al.

: Art Unit: 2841

Serial No.: 09/342,584

: Examiner: J. Alcala

Filed: June 29, 1999

FOR: PRINTED CIRCUIT BOARDS FOR
ELECTRONIC DEVICE PACKAGES HAVING
GLASS FREE NON-CONDUCTIVE LAYERS AND
METHOD OF FORMING SAME

SUPPLEMENTAL RESPONSE TO RESTRICTION REQUIREMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

S I R :

This Response is a supplement to the Response dated April 9, 2001. Please amend this application as indicated below and examine this application taking into consideration these amendments and remarks made below.

IN THE DRAWINGS:

Please amend Figure 3 as indicated in red on the enclosed copy of Figure 3.

IN THE SPECIFICATION:

Page 6, line 19.

Print circuit board 133 includes one or more plated through holes 124. The process of making plated through holes and circuitry is well known and not described here. Non-conductive layers 156, 158 insulate power planes 134, 152 from each other and from plated through hole 124 and from the glass fibers contained within substrates 114, 160. In this manner, shorts caused by electrochemical migration of conductive material between power planes 134, 152 and plated through hole 124 along glass fibers contained within substrates